

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0909LS	**Issued**	18. May 2021
MA#	MA005425682		
Package	PG-TSDSON-8-26	**Weight***	36.49 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.419	1.15	1.15	11475	11475
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		270	
	non noble metal	iron	7439-89-6	0.197	0.54		5392	
	non noble metal	copper	7440-50-8	7.988	21.89	22.47	218925	224654
wire	noble metal	gold	7440-57-5	0.029	0.08	0.08	801	801
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1023	
	plastics	epoxy resin	-	1.922	5.27		52664	
	inorganic material	silicondioxide	60676-86-0	16.698	45.77	51.14	457612	511299
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10833	10833
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	557	557
solder	non noble metal	tin	7440-31-5	0.013	0.03		348	
	noble metal	silver	7440-22-4	0.016	0.04		435	
	non noble metal	lead	7439-92-1	0.607	1.66	1.73	16631	17414
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		139	
	non noble metal	iron	7439-89-6	0.101	0.28		2776	
	non noble metal	copper	7440-50-8	4.112	11.27	11.56	112703	115653
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			32	
	non noble metal	zinc	7440-66-6	0.005	0.01		129	
	non noble metal	iron	7439-89-6	0.094	0.26		2576	
	non noble metal	copper	7440-50-8	3.816	10.46	10.73	104577	107314
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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